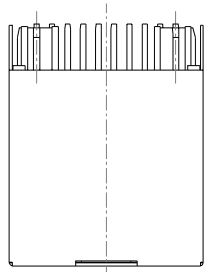
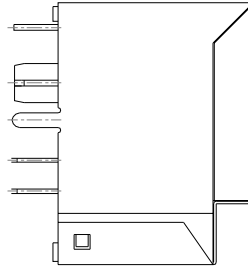


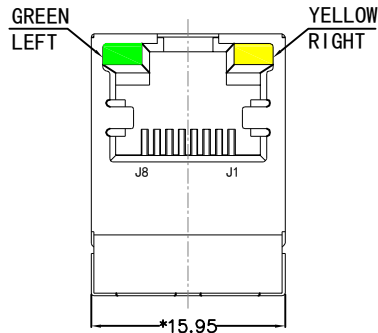
REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.	2020.07.06	



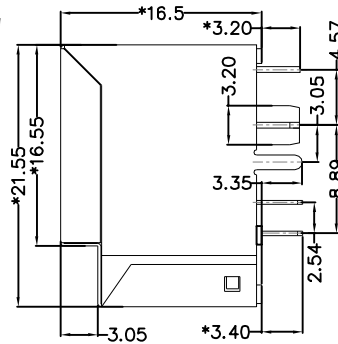
TOP VIEW



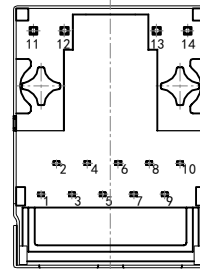
LEFT SIDE VIEW



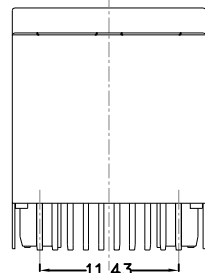
FRONT VIEW



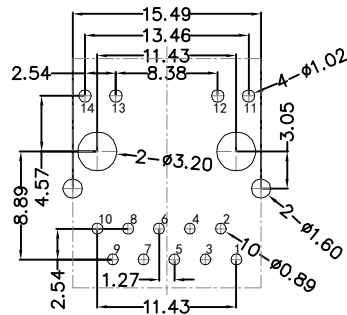
RIGHT SIDE VIEW



BACK VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT  
VIEWED FROM COMPONENT SIDE

**MATERIAL:**

HOUSING: PBT,UL94V-0,BLACK.  
 TERMINALS BRACKET: PBT,UL94V-0,BLACK.  
 SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.  
 TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,  
 6U" GOLD PLATING ON CONTACT AREA.

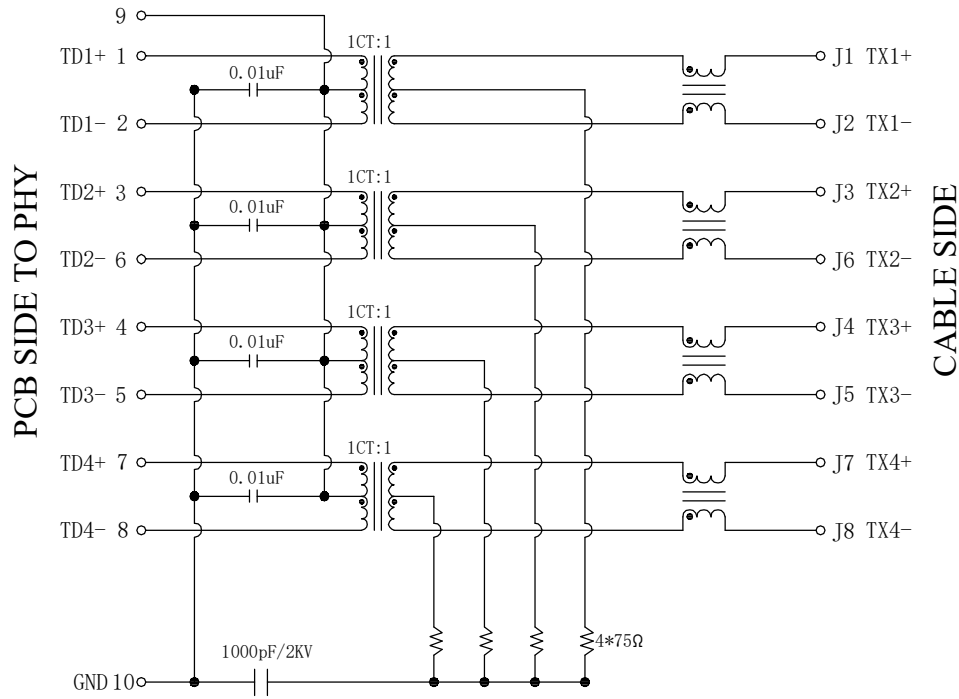
**MECHANICAL:**

DURABILITY: 750 CYCLES MIN.  
 MATING FORCE: 23N MAX.  
 OPERATING TEMPERATURE: -40°C~+85°C.  
 STORAGE TEMPERATURE: -40°C~+85°C.  
 ALL CRITICAL DIMENSIONS WITH "\*"



PART NO.		DRAWN	MARK
DRAWING NO.		CHECK	JOHN
TOLERANCE	X.±0.35 .X±0.30	APPROVE	MELODY
TITLE: TAB-UP 1*1 1000BASE	REV. A0	.XX±0.25 .XXX±0.10	SCALE 1:1 UNIT mm NO DESCRIPTION

REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.	2020.07.06	



CABLE SIDE

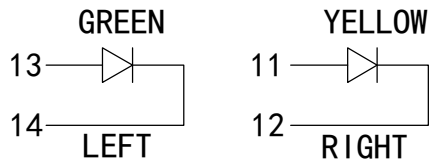
PCB SIDE TO PHY

**Electrical:**

- Turn ratio: 1~2: J1~J2=1CT:1CT(±2%).  
3~6: J3~J6=1CT:1CT(±2%).  
4~5: J4~J5=1CT:1CT(±2%).  
7~8: J7~J8=1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -18dB Min 1~30MHz;  
-14dB Min 30~60MHz.  
-12dB Min 60~80MHz.  
-10dB Min 80~100MHz.
- Cross talk: -40dB Min 1~30MHz;  
-35dB Min 30~60MHz;  
-30dB Min 60~100MHz;
- CMR: -30dB Min 1~100MHz;
- Hi-Pot: 2250V DC 6S 1mA PRI TO SEC

**LED Specification**

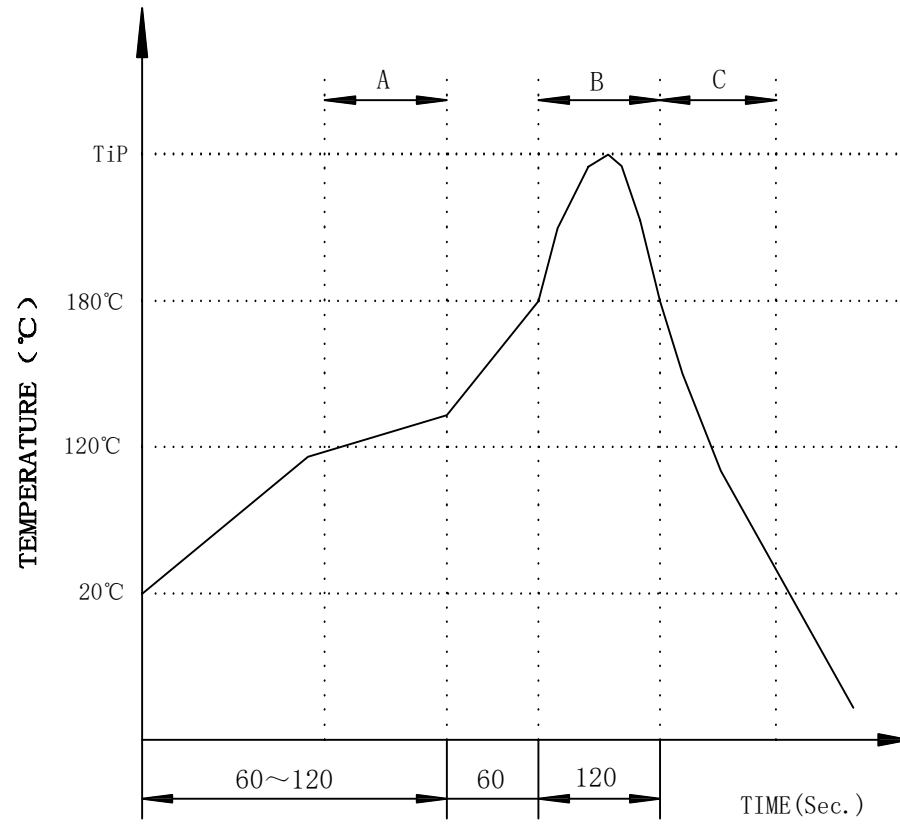
Standard LED Color	LED Wavelength	Foward(A)	Foward(V)
Green	568nm	20mA	1.85-2.45V
Yellow	585nm	20mA	1.7-2.2V



PART NO.		DRAWN	MARK
DRAWING NO.		CHECK	JOHN
TOLERANCE	X.±0.35 .X±0.30	APPROVE	MELODY
TITLE: TAB-UP 1*1 1000BASE	REV. A0	.XX±0.25 .XXX±0.10	SCALE 1:1 UNIT mm NO DESCRIPTION

REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.	2020.07.06	

# PROFILE OF WAVE SOLDER



A.Preheating B.Soldering C.Gradual Cooling  
 Tip temperature:260±5°C.  
 Tip temperature time:5Sec Max.  
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.



PART NO.		DRAWN	MARK
DRAWING NO.		CHECK	JOHN
TOLERANCE	X.±0.35 .X±0.30	APPROVE	MELODY
TITLE: TAB-UP 1*1 1000BASE	REV. A0	.XX±0.25 .XXX±0.10	SCALE 1:1 UNIT mm NO DESCRIPTION